

Final Product Change Notification

Issue Date: 12-Sep-2014 Effective Date: 24-Dec-2014

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201408010F01



Management Summary

Change to Samsung rough leadframe in production of IP4252CZ8-4-TTL at NXP assembly center APB (Bangkok, Thailand)

Change Category

[]\	Vafer Fab process	[] Assembly I	Process []Pro	oduct Marking	[X] Design
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[] Wafer Fab [X] Assembly [] Electrical spec./Test [] Mechanical Specification

materials Materials coverage

[] Wafer Fab location [] Assembly Location [] Test Location [] Packing/Shipping/Labeling

Change to Samsung rough leadframe in production of IP4252CZ8-4-TTL at APB

Details of this Change

Change to Samsung rough leadframe supplier for lead frames of IP4252CZ8-4-TTL (HUSON8) in our NXP assembly center APB (Bangkok, Thailand).

Leadframe design is improved to increase mechanical robustness.

After customer approval first shipments can be started immediately (see "Production" below).

Why do we Implement this Change

To increase production capacity and mechanical robustness.

Identification of Affected Products

not changed, identification by APB marking code on product

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 10-Dec-2014

Impact

no impact to product performance

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

not applicable.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Oct-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Carsten Lutterloh
Position Quality Manager

e-mail address carsten.lutterloh@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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High Tech Campus, 5656 AG Eindhoven, The Netherlands

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